

Tracewell T-FX2s

BASED ON: The Dell EMC PowerEdge FX architecture. Converged platform houses flexible blocks of server, storage and I/O resources while providing efficiency through shared power, networking and management.

USE CASE: Ideal for customers that need to integrate specialty PCle cards (GPU, I/O, FPGA), storage and other third-party technologies in order to support their high-performance and specialty computing needs.



8.7"H x 19.0"W x 23.7"D (17.5"W not including ears)

FORM FACTOR HIGHLIGHTS:

Short-depth form factor features an innovative, plug and play, modular tray that makes it possible to easily integrate specialty PCle cards (GPU, I/O, FPGA) into an enterprise class, converged platform.

Benefits

DELL TECHNOLOGIES

Enterprise-class modular infrastructure that combines the density and efficiency of blades with the simplicity and cost benefits of rack systems. Flexible and customizable servers, storage and networking.

TRACEWELL PLATFORMS

Features Dell EMC FX architecture in a short-depth form factor. Offers the ability to integrate full-size, high-power Gen 3 PCle cards in a pluggable module with up to 315W per PCle slot, including 8 full-size, single-width cards, 7 full-size, double-width cards or 4 full-size, double-width cards (x16).

DELL TECHNOLOGIES + TRACEWELL

Electrically identical to standard Dell EMC products. "Plug and play" components between Dell EMC products and Tracewell platforms. Order through Dell EMC (Dell EMC part number) and eligible for Dell EMC warranty, service, support and secure supply chain.

The Tracewell T-FX2s Specifications Summary

The Tracewell T-FX2s accepts standard Dell hardware configurations.

STANDARD DELL EMC PRODUCT CONFIGURATIONS

PROCESSOR TYPE	Quarter Width (QW): Intel® Xeon® E5-2600 v4 & v5 family of processors, up to 16 cores per processor (1 or 2 processors).
	Half Width (HW): Intel® 2nd generation Xeon® Scalable processors, up to 28 cores per processor (1 or 2 processors).
	Full Width (FW): Intel® Xeon® E5-4600 v3 & v4, up to 22 cores (4 processors).
MEMORY ARCHITECTURE	QW: 8 DDR4 slots, supports 2133MT/s LRDIMM and RDIMM, 512GB Max DDR4.
	HW: 16 DDR4 DIMM slots, supports RDIMM/LRDIMM, up to 2933MT/s speeds, 2TB Max DDR4.
RAID CONTROLLER	Hardware RAID, Levels 0, 1, 5, 10 or pass through.
STORAGE	Processing Sleds: QW: Up to two 1.8", HW: Up to two 2.5" or eight 1.8" drives, FW: Up to 16 1.8". Hot-swappable, SAS/SATA/PCIe, SSD/HDD.
	Storage Sleds: HW, up to 16 2.5" drives; Hot-swappable, SAS/SATA, SSD/HDD.
	Internal SD vFlash site; Optional internal USB and dual SD sites (hypervisor).
VIDEO	Internal SD vFlash site; Optional internal USB and dual SD sites (hypervisor).
SLED SLOTS	Sled bay scalable to include up to eight (QW), four (HW) or two (FW) processing sleds. Accepts standard FC430 and FC640 processing sleds and FD332 storage sleds with appropriate configuration or filler panels.
I/O MODULES	Ethernet: Supports up to 2 I/O aggregator modules. Modules are available in pass-through and switching configurations.
PCIe SLOTS	Supports PCle Gen3 full-height, full-length, high-performance cards.
	Up to (8) single wide x8, (7) double-side x8, or (4) double-wide x16 full-size cards.
	Front pluggable PCIe module is highly adaptable for specialized applications.
CHASSIS MANAGEMENT CONTROLLER	Single, dual-port chassis management module. Two dedicated 10/100/1000Mb RJ45 ports, one for external management, one for daisy chaining or NIC failover. Serial 9-pin, DTE, 16550 compatible.
FRONT ACCESSIBLE I/O	One USB 2.0 connector for keyboard and mouse support. One additional USB 2.0 connector. One 15-pin VGA video connector. KVM selector switch. On / Standby switch.

POWER SUPPLY	Up to four power supplies supported. Available in 2400W / 2000W / 1600W output (per PS). N+1 compatible.
	High-line operation up to 4750W* with N+1 redundancy or no-redundant.
	Low-line operation up to 4750W* with N+1 redundancy or non-redundant.
	Input voltage: 90-264 VAC.
	Maximum inrush current: 25 A (35A; 2400W).
	* CMC system limits power usage within the system architecture.
COOLING	Two rear removable fan modules with high pressure fans. Independent cooling provided to PCIe slots.

TRACEWELL SYSTEMS PRODUCT CONFIGURATIONS

CHASSIS	Bonded aluminum low-mass chassis for rigidity with minimum weight.
RACK INSTALLATION & OPTIONS	19" rack mount per EIA specification. Front and rear mounting points to allow hard mounting into racks; rear pin option allows blind mating intro racks. Additional mounting locations for sled lock bars. Front handles.
	Optional: Rugged transit case. Rack mount slides, removable front guard with particle filter and line cord retainer kit.

For more information, see the Tracewell T-FX2s Data Sheet.

ABOUT TRACEWELL SYSTEMS

For more than 40 years Tracewell has enabled the nation's largest military and commercial organizations to deliver powerful and reliable computing solutions in environments where size, weight, power and other constraints present challenges that cannot be met by standard computing systems. Tracewell Systems have been recognized by the top names in the defense and technology sectors for their commitment to Trusted Innovation – a process where the company solves previously impossible, sensitive, mission-critical platform challenges through customer solution design, engineering and manufacturing, all under one roof. More information: www.tracewell.com.

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